



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-04-30
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali-Palma	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	D5Y9*UQ36BA1	A	ZY1A	2014-04-30
Amount	UoM	Unit type	ST ECOPACK Grade	
109.426	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	9.7X4.4X0.9	36	gull wing	
Comment	Package: HTSSOP28 BODY4.4 PITCH0.65 EXPAD; MD valid for L6472H			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	DSY9*UQ368A1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	6.903	mg	supplier	DIE	Silicon (Si)	7440-21-3		6.594	mg	955237	60260
SILICON DIE			mg	supplier	metallization	Aluminium (Al)	7429-90-5		0.068	mg	9851	621
SILICON DIE			mg	supplier	metallization	Tungsten (W)	7440-33-7		0.054	mg	7823	493
SILICON DIE			mg	supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.014	mg	2028	128
SILICON DIE			mg	supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.116	mg	16804	1060
SILICON DIE			mg	supplier	passivation	Gamma-butyrolactone	96-48-0		0.038	mg	5505	347
SILICON DIE			mg	supplier	passivation	Polyhydroxyamide	55295-98-2		0.017	mg	2463	155
SILICON DIE			mg	supplier	passivation	Alcoxsilane	proprietary		0.001	mg	145	9
SILICON DIE			mg	supplier	passivation	Aryl Siliclic Acid	proprietary		0.001	mg	145	9
LEADFRAME	Copper and its alloy	50.206	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		48.054	mg	957137	439146
LEADFRAME			mg	supplier	ALLOY	Iron (Fe)	7439-89-6		1.158	mg	23065	10582
LEADFRAME			mg	supplier	ALLOY	Zinc (Zn)	7440-66-6		0.059	mg	1175	539
LEADFRAME			mg	supplier	ALLOY	Phosphorus (P)	7723-14-0		0.015	mg	299	137
LEADFRAME			mg	supplier	COATING	Silver(Ag)	7440-22-4		0.92	mg	18325	8408
DIE ATTACH	Other organic materials	0.012	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.001	mg	83333	9
DIE ATTACH			mg	supplier	GLUE	Epoxy resin B	68475-94-5		0.001	mg	83333	9
DIE ATTACH			mg	supplier	GLUE	Silver(Ag)	7440-22-4		0.007	mg	583333	64
DIE ATTACH			mg	supplier	GLUE	Lactone	96-48-0		0.001	mg	83333	9
DIE ATTACH			mg	supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.001	mg	83333	9
BONDING WIRE	Other inorganic materials	0.773	mg	supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	EC 417-470-1		0.001	mg	83333	9
ENCAPSULATION	Other inorganic materials	48.808	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.773	mg	1000000	7064
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Epoxy Resin	proprietary		4.382	mg	89780	40045
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		40.903	mg	838039	373796
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.243	mg	4979	2221
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Phenol Resin	proprietary		3.165	mg	64846	28924
ENCAPSULATION			mg	supplier	MOLDING COMPOUND	Bismuth (Bi)	7440-69-9		0.115	mg	2356	1051
FINISHING	Other inorganic materials	2.724	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2.724	mg	1000000	24894